ALPHA & OMEGA SEMICONDUCTOR

AO4419
P-Channel Enhancement Mode Field Effect Transistor

General Description

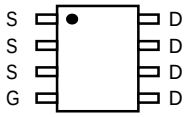
The AO4419 uses advanced trench technology to provide excellent $R_{DS(ON)}$, and low gate charge. This device is suitable for use as a load switch or in PWM applications.*Standard Product AO4419 is Pb-free (meets ROHS & Sony 259 specifications).*

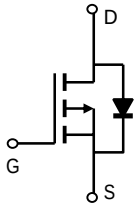
Features

V_{DS} (V) = -30V
I_D = -9.7 A (V_{GS} = -10V)
$R_{DS(ON)}$ < 20mΩ (V_{GS} = -10V)
$R_{DS(ON)}$ < 35mΩ (V_{GS} = -4.5V)

UIS TESTED!
Rg,Ciss,Coss,Crss Tested

SOIC-8
Top View





Absolute Maximum Ratings T_A=25°C unless otherwise noted

Parameter		Symbol	Maximum	Units
Drain-Source Voltage		V_{DS}	-30	V
Gate-Source Voltage		V_{GS}	±20	V
Continuous Drain Current [AF]	T_A=25°C	I_D	-9.7	A
	T_A=70°C		-8.1	
Pulsed Drain Current [B]		I_{DM}	-40	
Power Dissipation [A]	T_A=25°C	P_D	3	W
	T_A=70°C		2.1	
Avalanche Current [B, G]		I_{AR}	-30	A
Repetitive avalanche energy 0.1mH [B, G]		E_{AR}	45	mJ
Junction and Storage Temperature Range		T_J, T_{STG}	-55 to 150	°C

Thermal Characteristics

Parameter		Symbol	Typ	Max	Units
Maximum Junction-to-Ambient [AF]	t ≤ 10s	$R_{\theta JA}$	31	40	°C/W
Maximum Junction-to-Ambient [A]	Steady-State		63	75	°C/W
Maximum Junction-to-Lead [C]	Steady-State	$R_{\theta JL}$	21	30	°C/W

Electrical Characteristics (T_J=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV_{DSS}	Drain-Source Breakdown Voltage	I_D=-250µA, V_{GS}=0V	-30			V
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS}=-30V, V_{GS}=0V			-1	µA
		T_J=55°C			-5	
I_{GSS}	Gate-Body leakage current	V_{DS}=0V, V_{GS}=±20V			±100	nA
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS}=V_{GS} I_D=-250µA	-1.4	-2	-2.7	V
$I_{D(ON)}$	On state drain current	V_{GS}=-10V, V_{DS}=-5V	-40			A
$R_{DS(ON)}$	Static Drain-Source On-Resistance	V_{GS}=-10V, I_D=-9.7A		16	20	mΩ
		T_J=125°C		20.9	26	
		V_{GS}=-4.5V, I_D=-7A		26	35	mΩ
g_{FS}	Forward Transconductance	V_{DS}=-5V, I_D=-9.7A		21.7		S
V_{SD}	Diode Forward Voltage	I_S=-1A,V_{GS}=0V		-0.7	-1	V
I_S	Maximum Body-Diode Continuous Current				-1.2	A
DYNAMIC PARAMETERS						
C_{iss}	Input Capacitance	V_{GS}=0V, V_{DS}=-15V, f=1MHz		1573	1900	pF
C_{oss}	Output Capacitance			319		pF
C_{rss}	Reverse Transfer Capacitance			211	295	pF
R_g	Gate resistance	V_{GS}=0V, V_{DS}=0V, f=1MHz	3.3	6.7	8	Ω
SWITCHING PARAMETERS						
Q_g(10V)	Total Gate Charge (10V)	V_{GS}=-10V, V_{DS}=-15V, I_D=-9.7A		26.4	32	nC
Q_g(4.5V)	Total Gate Charge (4.5V)			13.7	17	nC
Q_{gs}	Gate Source Charge			3.8		nC
Q_{gd}	Gate Drain Charge			6.8		nC
$t_{D(on)}$	Turn-On DelayTime	V_{GS}=-10V, V_{DS}=-15V, R_L=1.5Ω, R_{GEN}=3Ω		9.5		ns
t_r	Turn-On Rise Time			8		ns
$t_{D(off)}$	Turn-Off DelayTime			44.2		ns
t_f	Turn-Off Fall Time			22.2		ns
t_{rr}	Body Diode Reverse Recovery Time	I_F=-9.7A, dI/dt=100A/µs		25.2	31	ns
Q_{rr}	Body Diode Reverse Recovery Charge	I_F=-9.7A, dI/dt=100A/µs		14.1		nC
t_{rr}	Body Diode Reverse Recovery Time	I_F=-9.7A, dI/dt=500A/µs		23	28	ns
Q_{rr}	Body Diode Reverse Recovery Charge	I_F=-9.7A, dI/dt=500A/µs		54		nC

A: The value of $R_{\theta JA}$ is measured with the device mounted on 1in 2 FR-4 board with 2oz. Copper, in a still air environment with T_A=25°C. The value in any given application depends on the user's specific board design.

B: Repetitive rating, pulse width limited by junction temperature.

C. The $R_{\theta JA}$ is the sum of the thermal impedence from junction to lead $R_{\theta JL}$ and lead to ambient.

D. The static characteristics in Figures 1 to 6 are obtained using <300 µs pulses, duty cycle 0.5% max.

E. These tests are performed with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with T_A=25°C. The SOA curve provides a single pulse rating.

F. The current rating is based on the t≤ 10s junction to ambient thermal resistance rating.

G: L=100uH, V_{DD}=0V, RG=0Ω, rated V_{DS}=30V and V_{GS}=10V

Rev5: May 2008

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

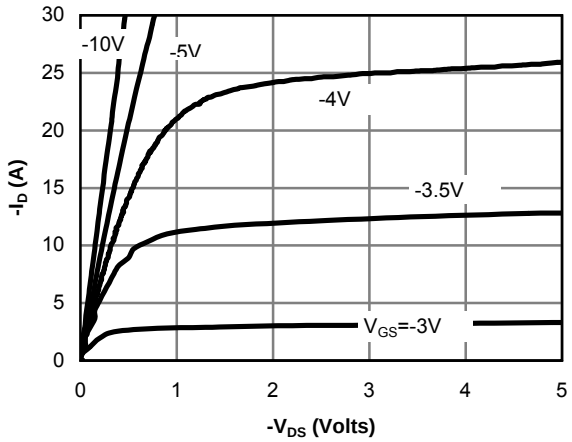


Fig 1: On-Region Characteristics

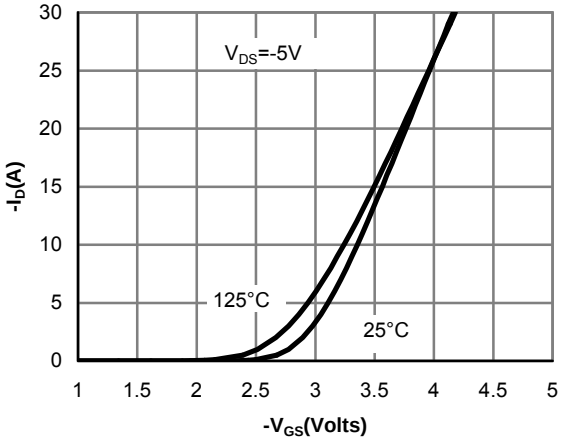


Figure 2: Transfer Characteristics

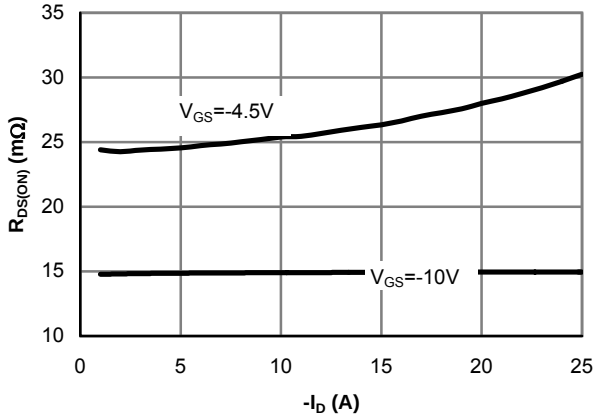


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

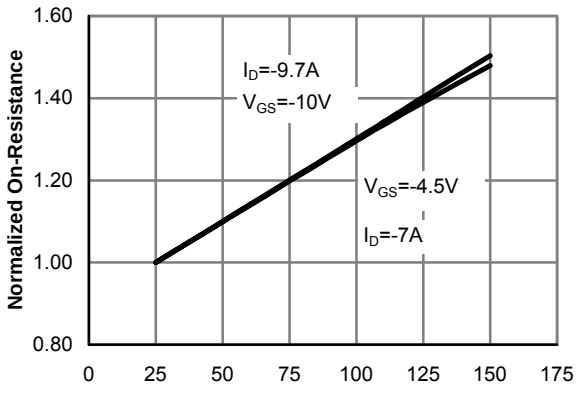


Figure 4: On-Resistance vs. Junction Temperature

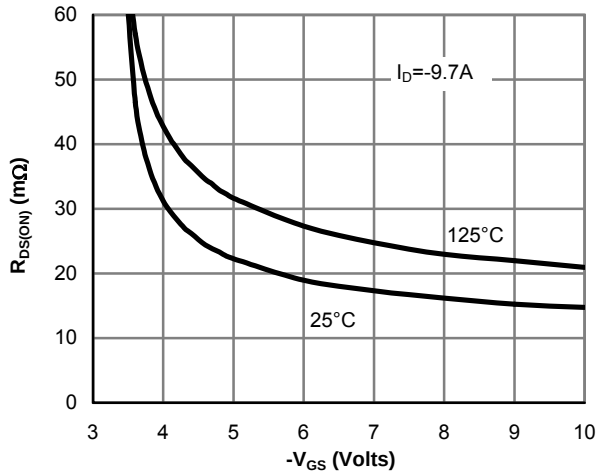


Figure 5: On-Resistance vs. Gate-Source Voltage

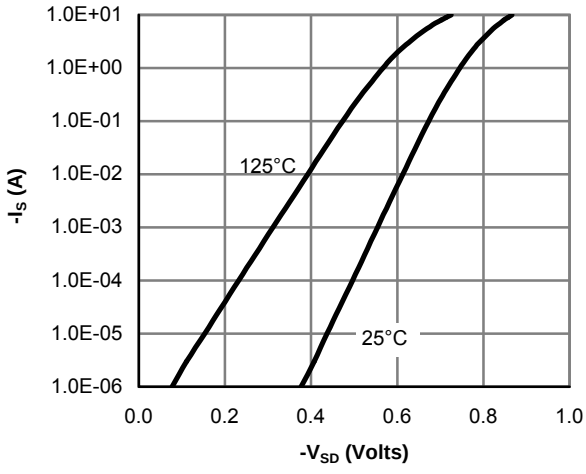


Figure 6: Body-Diode Characteristics

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

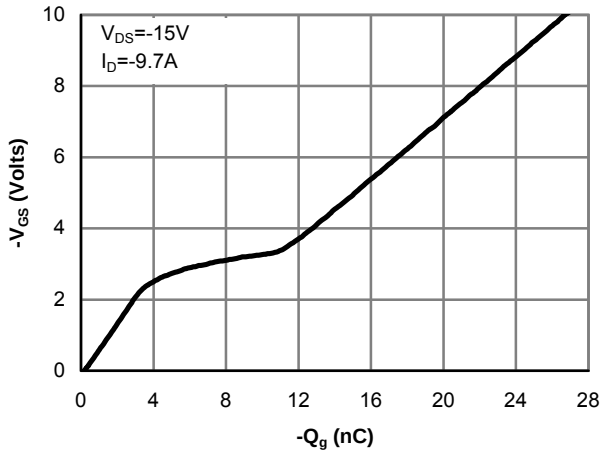


Figure 7: Gate-Charge Characteristics

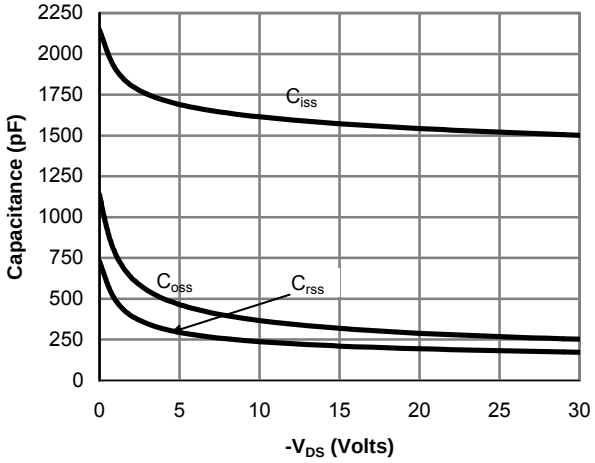


Figure 8: Capacitance Characteristics

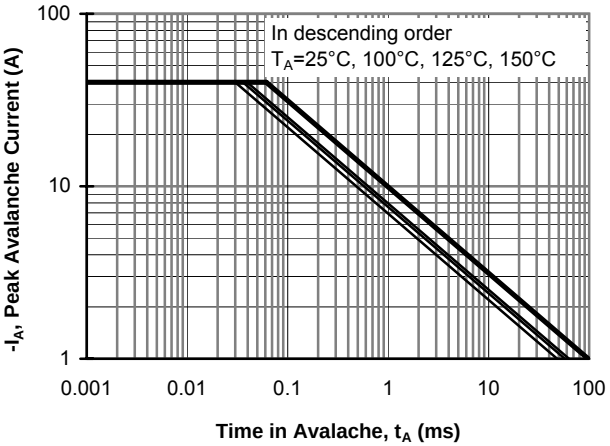


Figure 9: Single Pulse Avalanche Capability

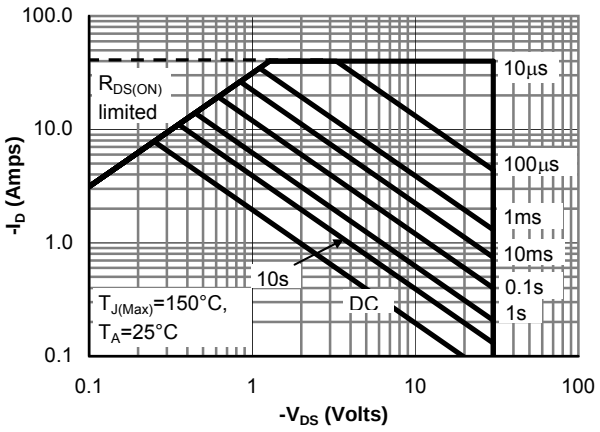


Figure 10: Maximum Forward Biased Safe Operating Area (Note E)

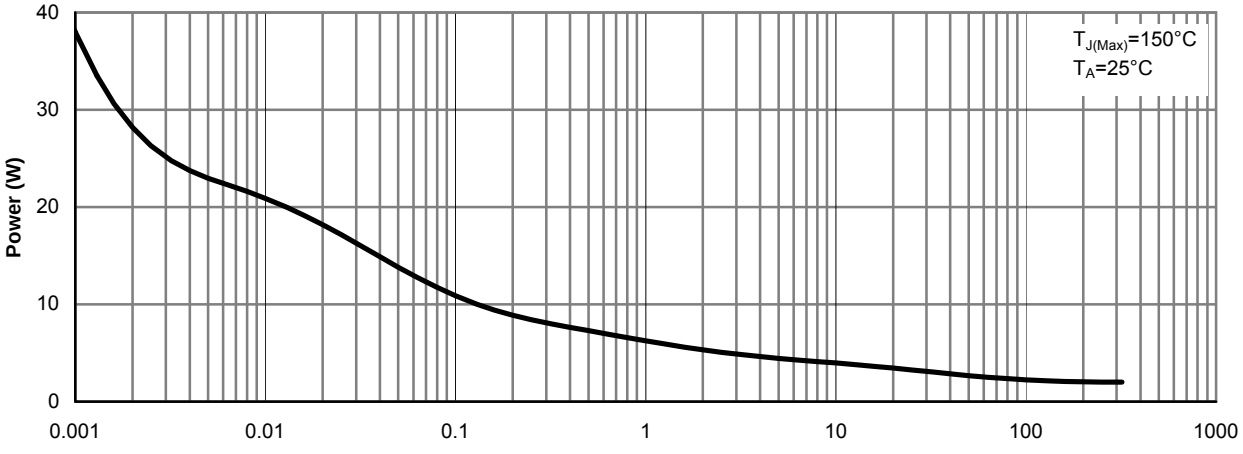


Figure 11: Single Pulse Power Rating Junction-to-Ambient (Note E)

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

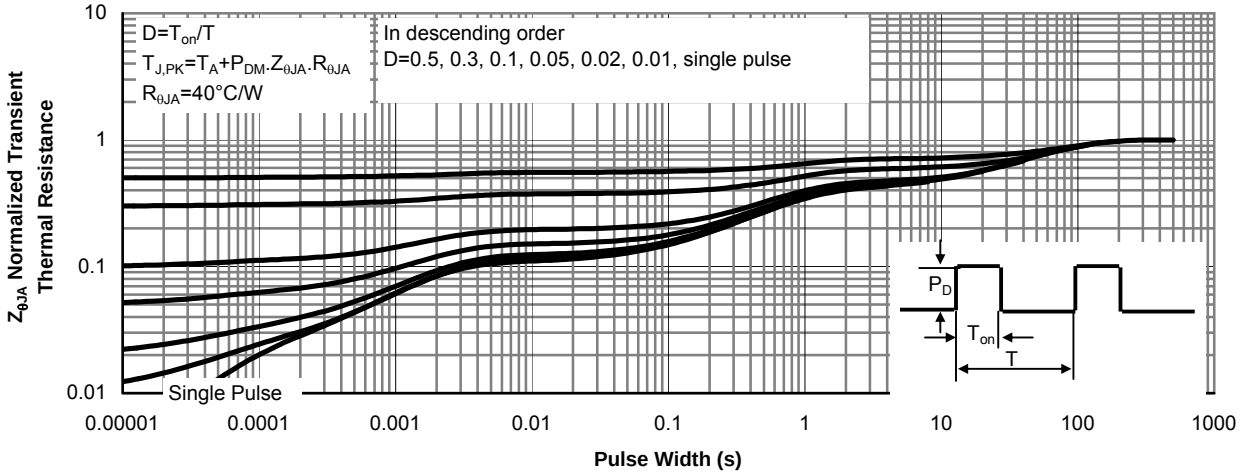


Figure 12: Normalized Maximum Transient Thermal Impedance